

DISTRIBUTION

Process Change Notice

Non cyanide stabilizer compound solution for Au plating process.


. Thank you very much for your support. We are currently using a material cyanide compounds, which is a poison, as a stabilizer for the gold plating bath in the plating process for terminal electrodes. , however we will change non cyanide compound for gold terminal plating solution. To reduce environmental risk and no limitation of factory equipment and location., There is no change that the plating material formed in the process is gold and it does not affect the quality.

Could you please give us first response by end of Sep.

.If there is no special offer by the end of December we would like to switch from the January 2020 production sequentially. Thank you for your understanding.

Factory location current
new location

TDK Akita in Japan ,
TDK Akita in Japan , TDK Dalian in China

Before		After			
cleaning		cleaning			
↓		↓			
rinsing		rinsing			
↓		↓			
catalist		catalist			
↓		↓			
rinsing		rinsing			
↓		↓			
electroless nickel plating		electroless nickel plating			
↓		↓			
rinsing		rinsing			
↓		↓			
substitution gold plating (cyan type)		substitution gold plating (non-cyan type)	← Change to disulfitoaurate type.		
↓		↓			
rinsing		rinsing			
↓		↓			
dry		dry			

Planned Date: 2020/Mar

Response Date By: 2019/Sep/30

Last Order date for current spec: 2019/Dec/31

Attachment : Yes

ANSWER SHEET

To TDK Corporation COMMUNICATION DEVICES BG	Company Department Name
Approval Date: _____	Directions

